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## Materials Declaration Form

<b>IPC Form Type *</b>	<b>1752</b> Distribute	<b>Version</b>	<b>2</b>
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2014-02-12
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Antonella Lanzafame	<b>Representative Title</b>	AMS/IPD Materials Declaration Champion)
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

Uncertainty Statement	
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Legal Statement	
<b>Supplier Acceptance *</b>	true
<b>Legal Declaration *</b>	Standard
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Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	A59U*UF37AJ6	A	MU1A	2014-02-12
Amount	UoM	Unit type	ST ECOPACK Grade	
653.38	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	250	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	7.5,15.4,2.50	24	gull wing	
Comment	SO 24 .30 TO JEDEC MS-013AD; MD valid for CP: L6207D, L6207D013TR.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	A59U*UF37A6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	14.484	mg	supplier	die	Silicon (Si)	7440-21-3		14.045	mg	969691	21496
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.107	mg	7387	164
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.012	mg	829	18
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.032	mg	2209	49
die (s)				supplier	passivation	Silicon Oxide (SiO2)	7631-86-9		0.185	mg	12773	283
die (s)				supplier	passivation	Gamma-butyrolactone	96-48-0		0.062	mg	4281	95
die (s)				supplier	passivation	Polyhydroxyamide	55295-98-2		0.028	mg	1933	43
die (s)				supplier	passivation	Alcoxysilane	proprietary		0.002	mg	138	3
die (s)				supplier	passivation	Aryl Siliclic Acid	proprietary		0.001	mg	69	2
die (s)				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.001	mg	69	2
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	138	3
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.007	mg	483	11
Leadframe	Copper & its alloys	199.965	mg	supplier	alloy	Copper (Cu)	7440-50-8		194.637	mg	973355	297892
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		4.578	mg	22894	7007
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.276	mg	1380	422
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.24	mg	1200	367
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.214	mg	1070	328
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.014	mg	70	21
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.006	mg	30	9
Soft solder	Solder	1.657	mg	supplier	solder	Silver (Ag)	7440-22-4		1.276	mg	770066	1953
Soft solder				supplier	solder	Epoxy Cresol Novolak	29690-82-2		0.374	mg	225709	572
Soft solder				supplier	solder	1-isopropyl-2,2-dimethyltrimethylene diisobu	6846-50-0		0.007	mg	4225	11
Bonding wire	Other inorganic materials	0.942	mg	supplier	wire	Gold (Au)	7440-57-5		0.942	mg	1000000	1442
encapsulation	Other Organic Materials	436.332	mg	supplier	mold compound	Silica, vitreous	60676-86-0		343.908	mg	788180	526352
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		30.092	mg	68966	46056
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		17.195	mg	39408	26317
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		25.793	mg	59113	39476
encapsulation				supplier	mold compound	Antimony Trioxide	1309-64-4		5.159	mg	11824	7896
encapsulation				JIG I	mold compound	Brominated Epoxy Resin	40039-93-8		6.448	mg	14778	9869
encapsulation				JIG I	mold compound	Brominated Epoxy Resin	40039-93-8		6.448	mg	14778	9869
encapsulation				supplier	mold compound	Carbon black	1333-86-4		1.289	mg	2954	1973